



PMEG4010EPK

40 V, 1 A low VF MEGA Schottky barrier rectifier

18 January 2018

Product data sheet

1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a leadless ultra small SOD1608 (DFN1608D-2) Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 1$ A
- Reverse voltage: $V_R \leq 40$ V
- Low forward voltage $V_F \leq 600$ mV
- Low reverse current
- AEC-Q101 qualified
- Solderable side pads
- Package height typ. 0.37 mm
- Ultra small and leadless SMD plastic package

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- LED backlight for mobile application
- Low power consumption applications
- Ultra high-speed switching
- Reverse polarity protection

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20$ kHz; $T_{amb} \leq 90$ °C; square wave	[1]	-	-	1	A
		$\delta = 0.5$; $f = 20$ kHz; $T_{sp} \leq 135$ °C; square wave		-	-	1	A
V_R	reverse voltage	$T_j = 25$ °C		-	-	40	V
V_F	forward voltage	$I_F = 1$ A; $t_p \leq 300$ μ s; $\delta \leq 0.02$; pulsed; $T_j = 25$ °C		-	540	600	mV
I_R	reverse current	$V_R = 10$ V; $T_j = 25$ °C		-	0.6	4	μ A

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
t _{rr}	reverse recovery time	I _F = 0.5 A; I _R = 0.5 A; I _{R(meas)} = 0.1 A; T _j = 25 °C		-	3	-	ns

[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al₂O₃, standard footprint.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 Transparent top view DFN1608D-2 (SOD1608)	 <i>sym001</i>
2	A	anode		

[1] The marking bar indicates the cathode.

6. Ordering information

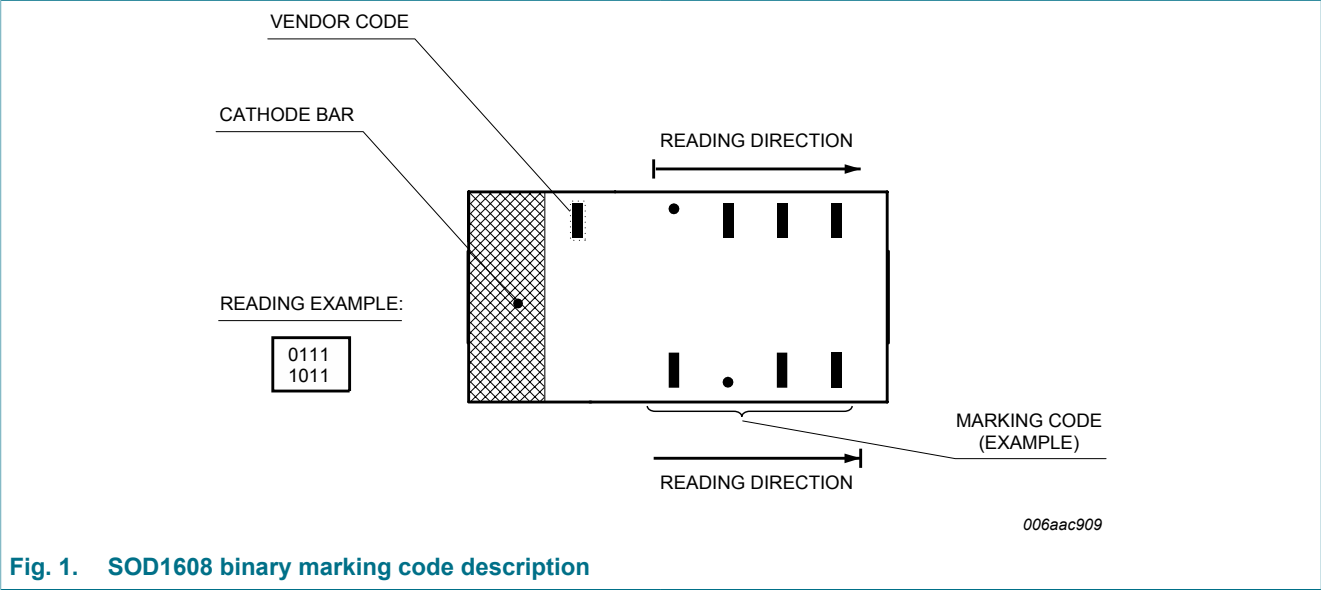
Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG4010EPK	DFN1608D-2	DFN1608D-2: leadless ultra small plastic package; 2 terminals	SOD1608

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG4010EPK	1010 0000



8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	$T_j = 25\text{ °C}$		-	40	V
I_F	forward current	$T_{sp} \leq 130\text{ °C}$		-	1.4	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20\text{ kHz}$; $T_{amb} \leq 90\text{ °C}$; square wave	[1]	-	1	A
		$\delta = 0.5$; $f = 20\text{ kHz}$; $T_{sp} \leq 135\text{ °C}$; square wave		-	1	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1\text{ ms}$; $\delta \leq 0.25$		-	3	A
I_{FSM}	non-repetitive peak forward current	$t_p = 8\text{ ms}$; square wave; $T_{j(init)} = 25\text{ °C}$		-	5	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[2] [3]	-	410	mW
			[4] [3]	-	860	mW
			[1] [3]	-	1565	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C

[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3 , standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Reflow soldering is the only recommended soldering method.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2] [3]	-	-	305	K/W
			[1] [4] [3]	-	-	145	K/W
			[1] [5] [3]	-	-	80	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[6]	-	-	20	K/W

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Reflow soldering is the only recommended soldering method.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

[5] Device mounted on a ceramic PCB, Al_2O_3 , standard footprint.

[6] Soldering point of cathode tab.

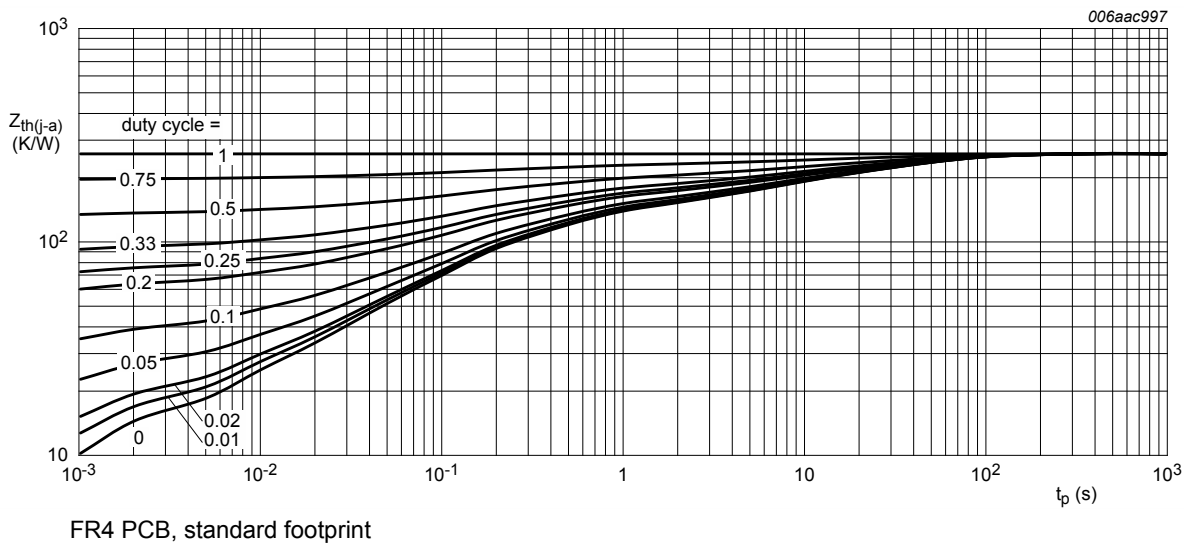


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

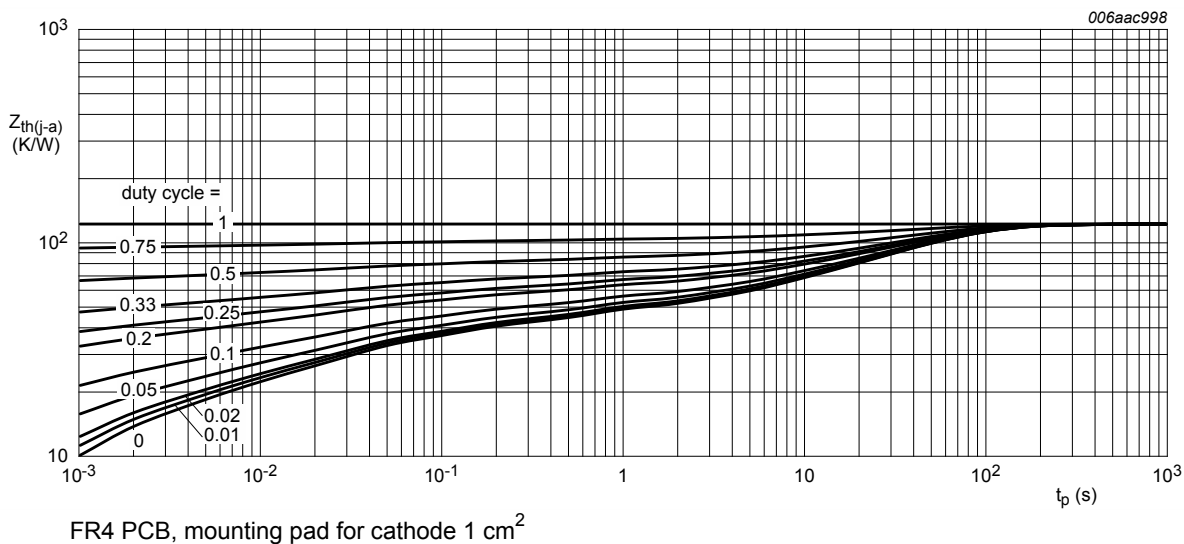
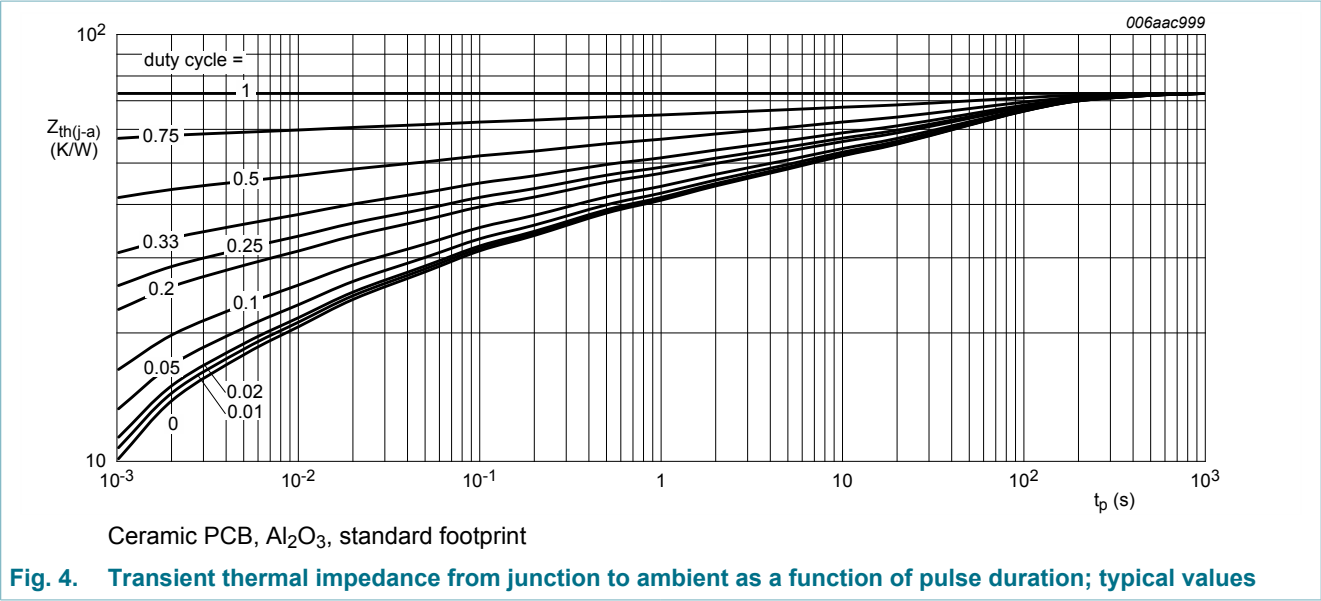


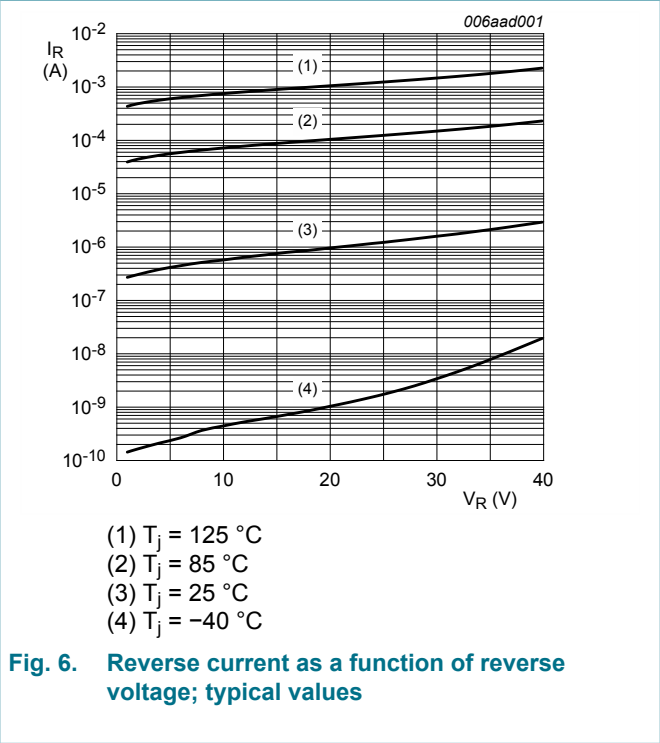
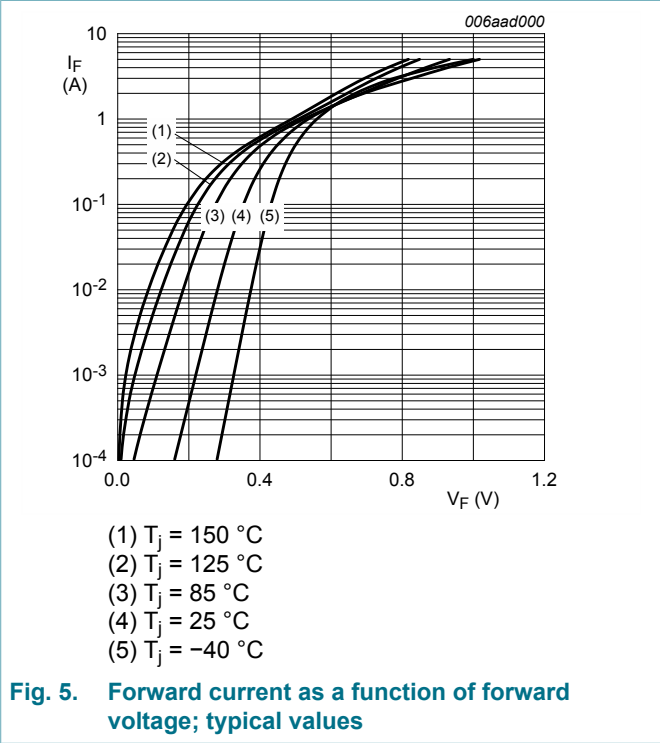
Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

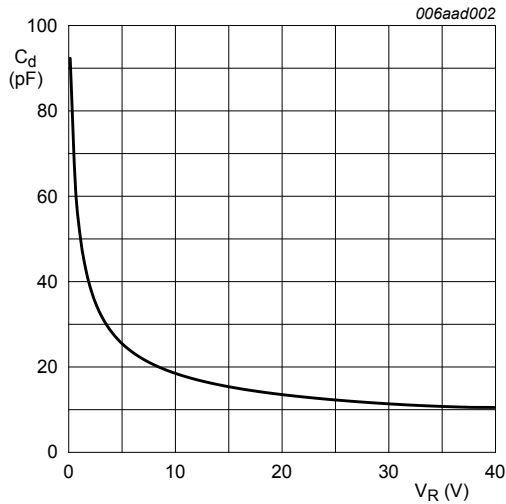


10. Characteristics

Table 7. Characteristics

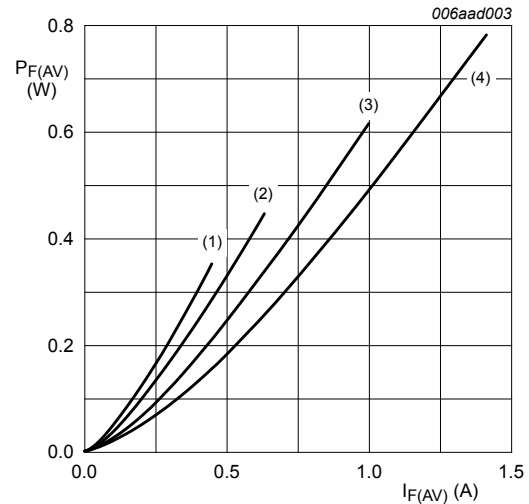
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _F	forward voltage	I _F = 100 mA; t _p ≤ 300 μs; δ ≤ 0.02 ; pulsed; T _j = 25 °C	-	345	390	mV
		I _F = 500 mA; t _p ≤ 300 μs; δ ≤ 0.02 ; pulsed; T _j = 25 °C	-	440	500	mV
		I _F = 700 mA; t _p ≤ 300 μs; δ ≤ 0.02 ; pulsed; T _j = 25 °C	-	480	550	mV
		I _F = 1 A; t _p ≤ 300 μs; δ ≤ 0.02 ; pulsed; T _j = 25 °C	-	540	600	mV
I _R	reverse current	V _R = 10 V; T _j = 25 °C	-	0.6	4	μA
		V _R = 40 V; T _j = 25 °C	-	3	20	μA
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _j = 25 °C	-	50	60	pF
		V _R = 10 V; f = 1 MHz; T _j = 25 °C	-	20	25	pF
t _{rr}	reverse recovery time	I _F = 0.5 A; I _R = 0.5 A; I _{R(meas)} = 0.1 A; T _j = 25 °C	-	3	-	ns
V _{FRM}	peak forward recovery voltage	I _F = 0.5 A; dI _F /dt = 20 A/μs; T _j = 25 °C	-	460	-	mV





$f = 1 \text{ MHz}$; $T_{\text{amb}} = 25 \text{ }^{\circ}\text{C}$

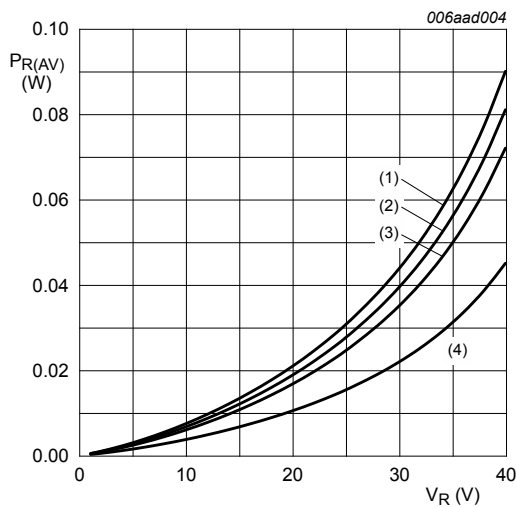
Fig. 7. Diode capacitance as a function of reverse voltage; typical values



$T_j = 150 \text{ }^{\circ}\text{C}$

- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 1$

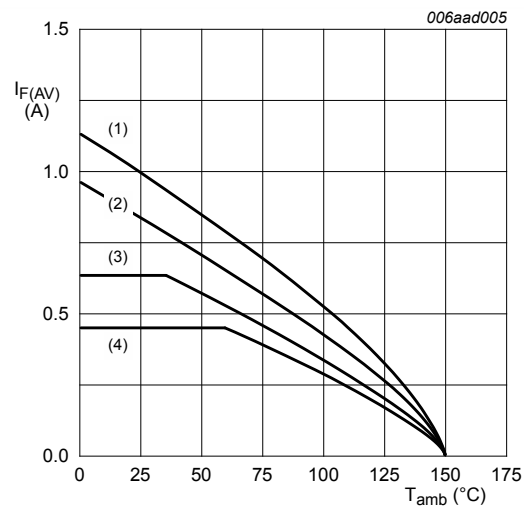
Fig. 8. Average forward power dissipation as a function of average forward current; typical values



$T_j = 125 \text{ }^{\circ}\text{C}$

- (1) $\delta = 1$
- (2) $\delta = 0.9$
- (3) $\delta = 0.8$
- (4) $\delta = 0.5$

Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values

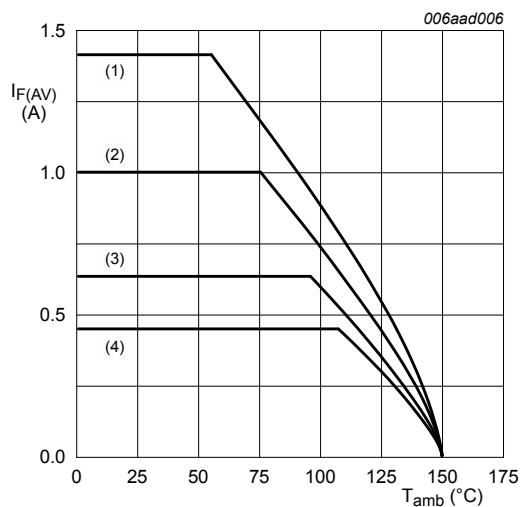


FR4 PCB, standard footprint

$T_j = 150 \text{ }^{\circ}\text{C}$

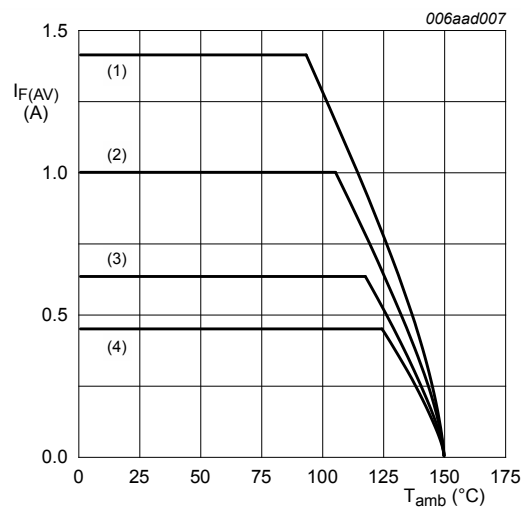
- (1) $\delta = 1$ (DC)
- (2) $\delta = 0.5$; $f = 20 \text{ kHz}$
- (3) $\delta = 0.2$; $f = 20 \text{ kHz}$
- (4) $\delta = 0.1$; $f = 20 \text{ kHz}$

Fig. 10. Average forward current as a function of ambient temperature; typical values



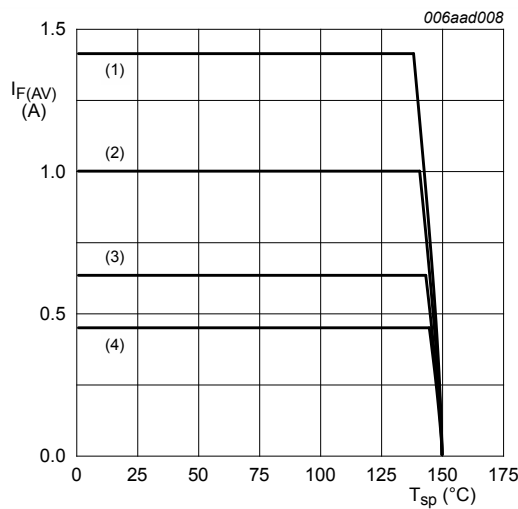
FR4 PCB, mounting pad for cathode 1 cm²
 $T_j = 150\text{ °C}$
(1) $\delta = 1$ (DC)
(2) $\delta = 0.5$; $f = 20\text{ kHz}$
(3) $\delta = 0.2$; $f = 20\text{ kHz}$
(4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 11. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al₂O₃, standard footprint
 $T_j = 150\text{ °C}$
(1) $\delta = 1$ (DC)
(2) $\delta = 0.5$; $f = 20\text{ kHz}$
(3) $\delta = 0.2$; $f = 20\text{ kHz}$
(4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 12. Average forward current as a function of ambient temperature; typical values



$T_j = 150\text{ °C}$
(1) $\delta = 1$ (DC)
(2) $\delta = 0.5$; $f = 20\text{ kHz}$
(3) $\delta = 0.2$; $f = 20\text{ kHz}$
(4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 13. Average forward current as a function of solder point temperature; typical values

11. Test information

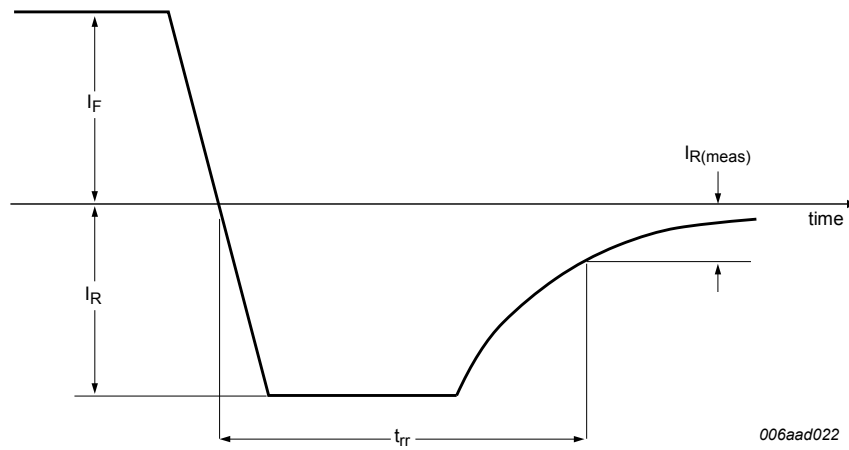


Fig. 14. Reverse recovery definition

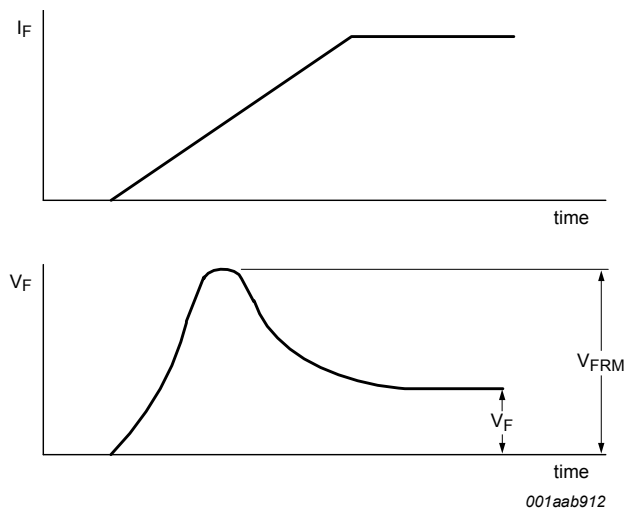


Fig. 15. Forward recovery definition

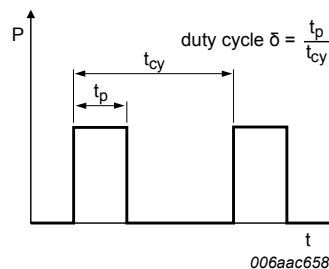


Fig. 16. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:
 $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

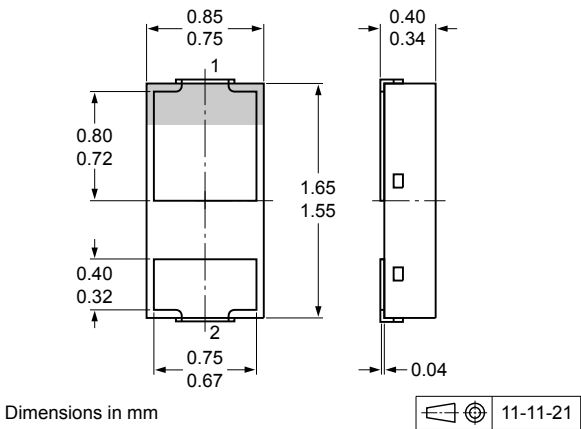


Fig. 17. Package outline DFN1608D-2 (SOD1608)

13. Soldering

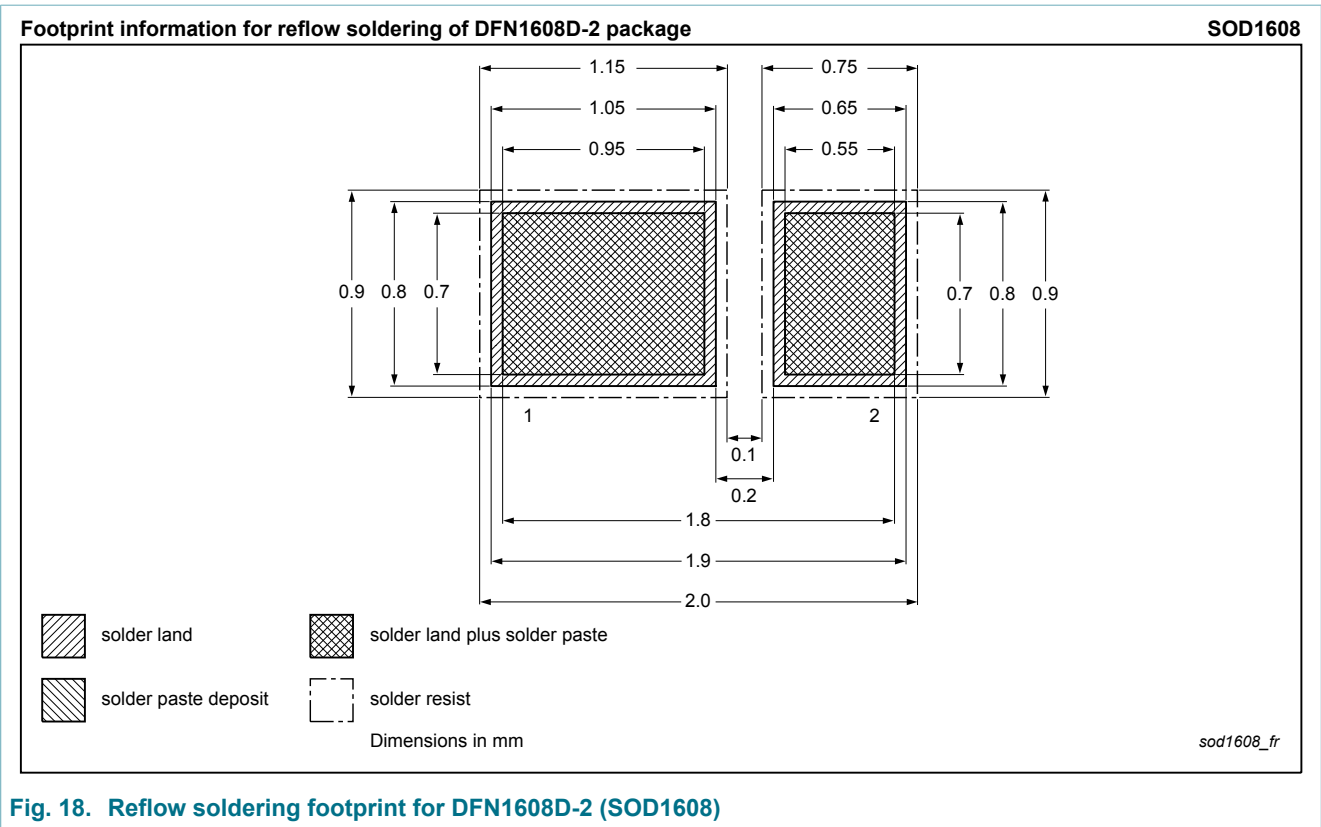


Fig. 18. Reflow soldering footprint for DFN1608D-2 (SOD1608)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG4010EPK v.3	20180118	Product data sheet	-	PMEG4010EPK_2
Modifications:	- The format of this datasheet has been redesigned to comply with the identity guidelines of Nexperia. - Legal texts have been adapted to the new company name where appropriate.			
PMEG4010EPK_2	20120306	Product data sheet	-	PMEG4010EPK_1
PMEG4010EPK_1	20120302	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 18 January 2018

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